

产品承认书

SPECIFICATION FOR APPROVAL

CUSTOMER:	
CUSTOMER P/N:	
CND-TEK P/N. :	G9602D
DESCRIPTION:	HIGH POE+ (1.7A) ENABLED TRANSFORMER 10/100/1000 BASE-T QUAD PORT THROUGH-HOLE MAGNETICS
REF NO:	QTC-001
REV/NO:	V1.02
DATE:	2015/03/02

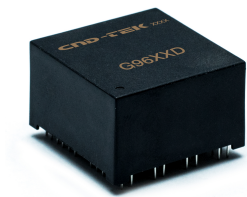
ATTACHMENT:			
■ SPECIFICATION			
■ SAMPLE	Q'TY OF SAMPLES	PCS	

	√	CUSTOMER'S SIGNATURE	REMARK
FULL APPROVED			
CONDITIONAL APPROVED			
REJECTED			

CND-TEK

G9602D

**HIGH POE+ (1.7A) ENABLED
TRANSFORMER 10/100/1000 BASE-T
QUAD PORT THROUGH-HOLE
MAGNETICS**



V1.0.2
Feb 2, 2015

CND-TEK

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1. FEATURES:

1.1 10/100/1000 BASE-T QUAD PORT THROUGH-HOLE MAGNETICS

1.2 Meets IEEE 802.3at & ANSI X3.263 Standards.

1.3 Suitable For End-span and Mid-span POE+ Applications.

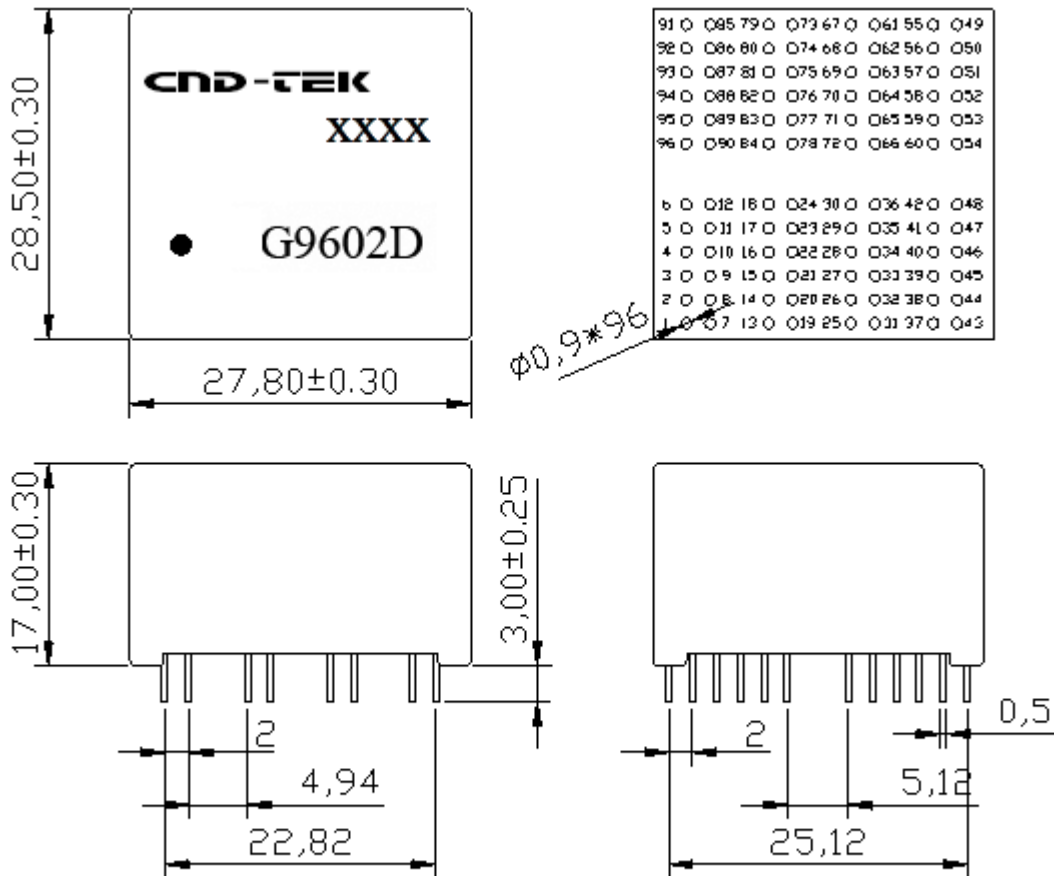
1.4 850mA Current Capability Per POE Port

1.5 RoHS Compliant

1.6 Operating Temperature range: 0°C TO +70°C

1.7 Storage temperature range: -25°C TO +125°C

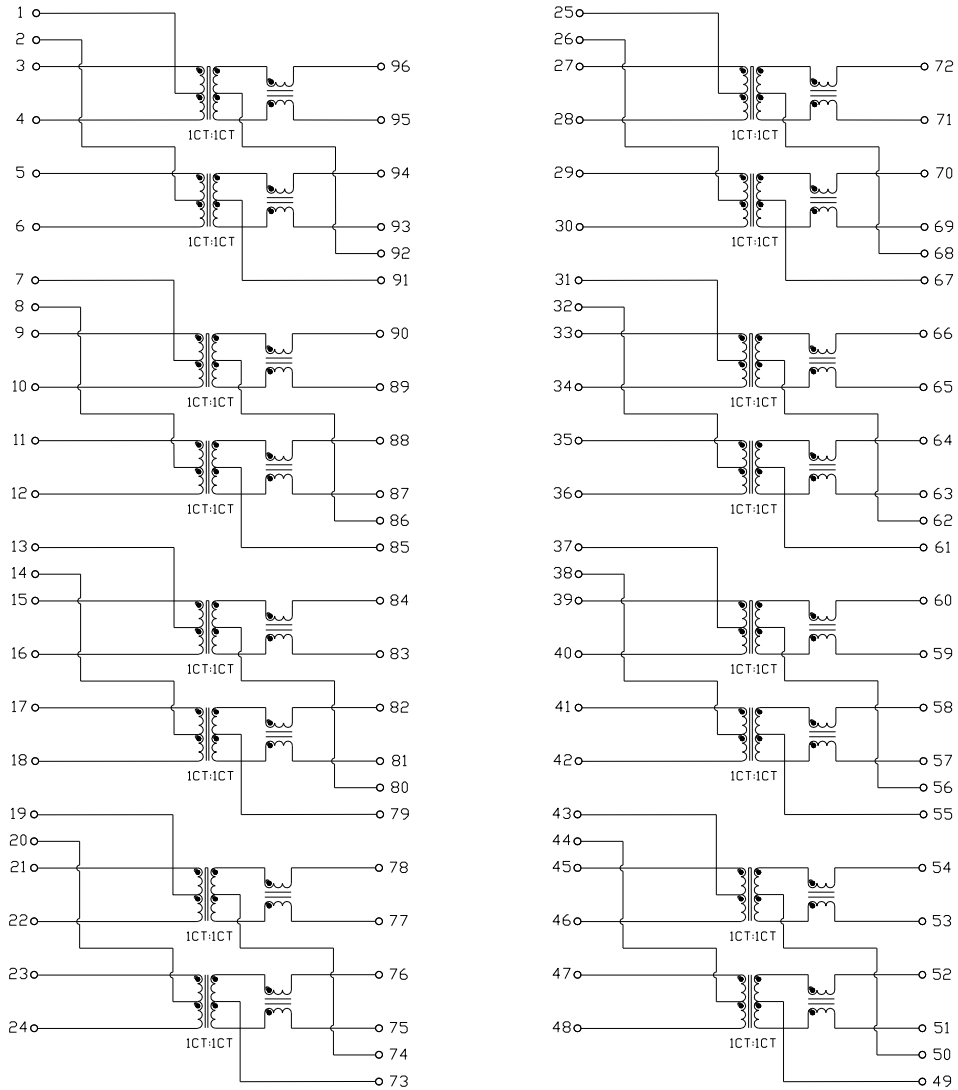
2. DIMENSIONS & MARKING



Note: 1、 Dimension: mm

2、 Unless otherwise specified, all tolerances are: $\pm 0.05\text{mm}$

3. SCHEMATICS:



4. ELECTRICAL SPECIFICATIONS @25°C

4.1 OCL : 350 μ H Min. @ 100 KHz, 100mV with 8mA DC Bias

4.2 Leakage Inductance: 0.5 μ H Max. @ 100KHz, 0.2V

4.3 Cw/w: 35 pF Max. @ 100KHz, 0.2V

4.4 DCR: 1.20 Ω Max.

4.6 Insertion Loss -1.2 dB Max. (TX & RX)@ 1~100 MHz

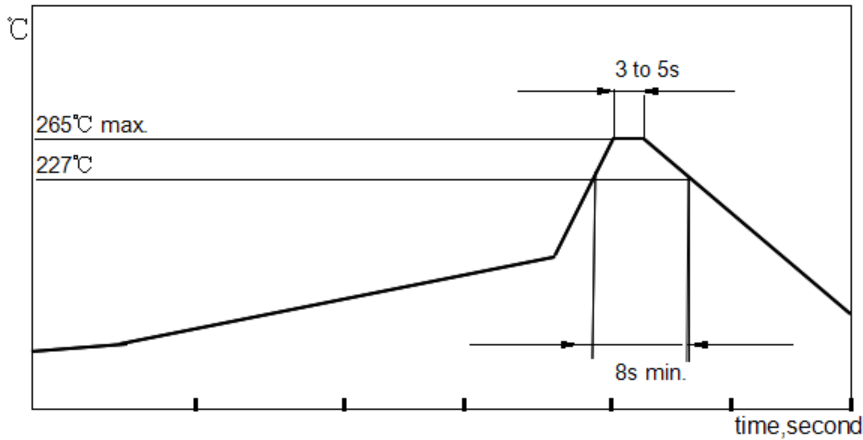
4.7 Return Loss: -16 dB Min @ 0.5-40MHz
 -10+20*log(f/80) dB Min @ 40.1-100 MHz

4.8 Cross Talk: -50 dB Min.@ 1~10 MHz
 -55+22*log(f/10) dB Min.@ 10~100 MHz

4.9 Common Mode Rejection : -50 dB Min.@ 2 MHz

-15+20*log(f/200) dB Min.@ 30~200 MHz
4.10 Isolation HI-POT: 1500Vrms 1mA 1Second

5. Recommended Lead Free IR Reflow Soldering Curve :



Item	Soldertechnique simulation	Temperature (°C)	Time(s)	Temperature ramp/immersion and emersion rate
1	Solder iron	350 ± 10 (solder irno temp)	4~5	
2	Vapor phase reflow	215 ± 5 (vapor temp)	60 ± 5	
3	IR/convection reflow	255 ± 5 (component temp)	30 ± 5	1°C/s~4°C/s time above 183°C 90s~120s

Note: The curve includes recommended value only, please adjust your equipment to make sure the solder process.Details please refers to the standard J-STD-020.

6. Reliability Test Criteria:

6.1 Terminal strength: Pull test withstand 9.8N 60+/-0.5S no looseness or movement.

6.2 Solderbility: Dipped in 245°C+/-5°C molten solder for 3+/-0.5 seconds,95% min shall be smooth any and bright.

6.3 Resistance to soldering heat : Convection reflow condition setting: peak temperature at 260°C+0/-5°C above 217°C for 90-180 seconds, ramp-up rate 2-3°C/s. Ramp-down rate 6°C/s Max. No mechanical problem found. No electrical failure found per our specification.

6.4 Vibration: 1.5mm amplitude total excursion 10-55-10 Hz traversed in 1minute, x.y.z, axis for 2 hours. Shall not be any abnormality.

6.5 Random drop (Packing condition): Height 60cm, 3 times on the wood floorboard ,shall not be any abnormality.

6.6 Dry heat: 100+/-2°C 96 hours.

6.7 Cold: -20+/-2°C 96 hours.

6.8 Damp Heat: 60+/-2°C, 93+/-3% RH 96 hours.

6.9 Change of temperature: exposed 5 cycle; each consisting of 30 minutes at -20+/-2°C,2-3minutes at 20+/-2°C,30 minutes at 85+/-2°C, 2-3 minutes at 20+/-2°C.